



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **Miwa KOZAWA et al.**

Group Art Unit: **1752**

Application Number: **10/629,806**

Examiner: **Sin J. Lee**

Filed: **July 30, 2003**

Confirmation Number: **9494**

For: **RESIST PATTERN THICKENING MATERIAL, PROCESS FOR
FORMING RESIST PATTERN, AND PROCESS FOR
MANUFACTURING SEMICONDUCTOR DEVICE**

Attorney Docket Number: **030923**

Customer Number: **38834**

SUBMISSION UNDER 37 C.F.R. §1.114

Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

February 2, 2007

Sir:

This Submission is being filed concurrently with a Request for Continued Examination pursuant to 37 C.F.R. §1.114.

Amendments to the Claims begin on page 2 of this paper.

Remarks begin on page 9 of this paper.

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